

EUV Mask Metrology via Ptychography

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Project objective

The successful implementation of extreme ultraviolet lithography (EUVL) for the next-generation technology nodes depends critically on the availability of EUV mask technology and related actinic (@13.5 nm) mask metrology. In particular, we are investigating sub-wavelength resolution using model based estimates of parametrized a-periodic features which are of interest owing to current trends in the lithography industry.

Motivation

Metrology of 3D EUV masks is important for:

- Detection of mask defects in the patterned absorber
- Control proper absorber patterning

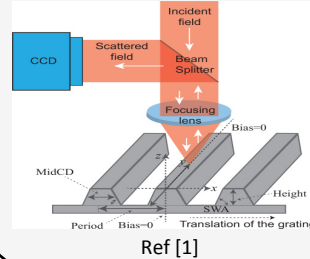


Patterned absorber image courtesy of ASML

Scatterometry and Ptychography

Far-field diffraction-based metrology will be employed. We will complement the technique of X-ray ptychography making use of prior information about the target, given by the lithographic mask, to extend metrology to a-periodic samples..

Optical Scatterometry



Ref [1]

Soft X-Ray Ptychography

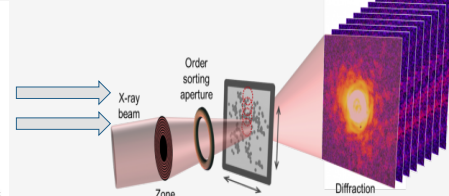
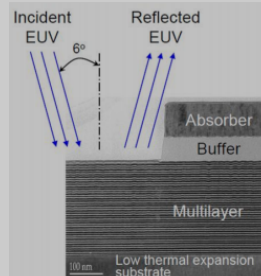


Image : Stanford Synchrotron radiation lightsource

Materials

The absorber pattern lays upon a Si/MoSi2/Mo/MoSi2 multilayer that enables reflection of EUV light.



Stack (Bottom to Top):

Material	n	k	Thickness
Ru	0.88586	0.01727	0.5 nm
TaBN	0.95	0.031	58 nm
TaBO	0.952	0.026	2 nm

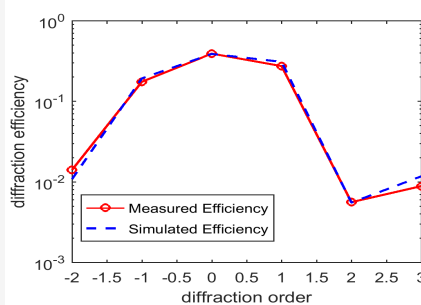
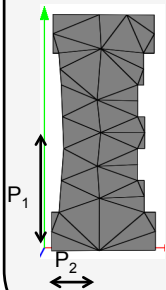
Multilayer:

Material	n	k	Thickness
Si	0.99888	0.00183	1.8968 nm
MoSi2	0.96908	0.00435	0.7986 nm
Mo	0.92347	0.00649	2.496 nm
MoSi2	0.96908	0.00435	0.7986 nm

Image: "Overview of EUV Mask Metrology"- SEMATECH Inc.

Numerical results

We consider as a first test case a mask with periodic 3D absorber profile as shown.



$$\chi^2 = \sum_{n=1}^N \sum_{j=1}^M \left(\frac{I_{nj}^{meas} - I_{nj}^{sim}}{I_{nj}^{meas}} \right)^2$$

Parameter	Nominal Value [nm]	Reconstructed Value [nm]	σ [nm]
P ₁	-42.5	-41.2	1.21
P ₂	-13.38	-12.85	0.45

References

- [1] N.Kumar, P. Petrik, G.K.P. Ramanandan, O. El Gawhary, S. Roy, S. F. Pereira, W. M. J. Coene and H. P. Urbach, Opt. Express Vol. 22, pp. 24678-24688 (2014)
[2] J. M. Rodenburg and H. M. L. Faulkner, Appl. Phys. Lett., 85:4795-4797, (2004)
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